Co-packaged optical and silicon photonics modules

Overview

This article provides a comprehensive overview of CPO optical modules, exploring their technology, benefits, challenges, and the pivotal role they play in future data centers and AI infrastructure. CPO optical modules put optical and electronic parts together. The silicon photonics industry is entering a period of rapid growth and diversification, according to Yole Group 's new report, Silicon Photonics 2025 – Focus on SOI, SiN, LNOI & InP Platforms. As AI continues to drive exponential demand for bandwidth, the sector is transitioning to higher data. Abstract—We present our work in the area of heterogeneous opticalintegration,whereseparatelymanufacturedelectroniccom-ponents are assembled on to an active silicon photonics interposer to form a higher-level component. This process allows for the integration of components independently designed and. GF's SCALE solution, or Silicon photonics Co-packaged Advanced Light Engine solution, is the industry's first Optical Compute Interconnect Multi-Source Agreement (OCI MSA) capable platform, exceeding the requirements for the OCI MSA's optical interconnect specification for modern AI scale-up. NVIDIA is developing a co-packaged optics (CPO) platform that integrates optical and electrical components to improve data-center connectivity, in collaboration with industry partners like TSMC. According to ZDNet, the company said in its 1Q26 earnings release that its foundry has secured orders from a major optical communication module provider.

Article Content

GF accelerates adoption of co-packaged optics for AI data centers

GlobalFoundries (GF) has announced the introduction of its SCALE optical module solution for co-packaged optics (CPO). GF''s SCALE solution, or Silicon photonics Co-packaged

GlobalFoundries accelerates adoption of co-packaged optics for

MALTA, N.Y., May 4, 2026 – GlobalFoundries (Nasdaq: GFS) (GF) today announced the introduction of its SCALE™ optical module solution for co-packaged optics (CPO). GF''s SCALE solution, or Silicon

Samsung Foundry Reportedly Wins Optical Module Order,

As a result, optical transmission technologies are becoming increasingly important. TrendForce forecasts that co-packaged optics (CPO) will steadily increase their share of optical

GlobalFoundries unveils silicon photonics platform

GlobalFoundries has introduced a new silicon photonics platform designed to support co-packaged optics.

1.6 Tbps FOWLP-Based Silicon Photonic Engine for Co-Packaged

The FOWLP platform enables the seamless integration of Electronic ICs (EICs) and Photonic ICs (PICs) without wire bonds, preserving signal integrity and minimizing losses.

How Industry Collaboration Fosters NVIDIA Co

NVIDIA is developing a co-packaged optics (CPO) platform that integrates optical and electrical components to improve data-center connectivity,

Intel® Silicon Photonics

Hands-on with the Intel Co-Packaged Optics and Silicon Photonics Switch Patrick Kennedy from ServeTheHome got to check out Intel''s live demonstration of co-packaged optics switch passing

The Rise of Co-Packaged Optics: A Deep Dive into

Enter Co-Packaged Optics (CPO), a transformative architecture where the optical engine moves inside the switch ASIC package. This article provides a

NVIDIA Pulls In Co-Packaged Optics by 5 Years: How Japanese Photonics ...

GPU-to-GPU optical interconnects were forecast to arrive around 2033. NVIDIA just pulled them in by five years, announcing they will ship in the 2028 Feynman GPU generation. As Co

Marvell Announces Breakthrough Co-Packaged Optics

Multiple customers are evaluating the technology for integration into their next-generation solutions. For more than eight years, Marvell has delivered

Silicon Photonics and Co-Packaged Optics at the Heart

Yole Group unveils its latest photonic market and technology analyses, Silicon Photonics 2025 and Co-Packaged Optics for Data Centers

GlobalFoundries accelerates adoption of co-packaged optics for

GF''s SCALE solution, or Silicon photonics Co-packaged Advanced Light Engine solution, is the industry''s first Optical Compute Interconnect Multi-Source Agreement (OCI MSA) capable

The Evolution of Optical Modules: 400G → 800G → 1.6T – A Strategic ...

Over the past five years, data center interconnects have transitioned from incremental upgrades to a dramatic shift. With 400G modules now the baseline, 800G adoption is

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GlobalFoundries Advances Co-Packaged Optics for AI

GlobalFoundries has announced the introduction of its SCALE™ optical module solution for co-packaged optics (CPO). GF''s SCALE solution, or Silicon Photonics Co-packaged Advanced

GlobalFoundries accelerates adoption of co-packaged optics for

SCALE CPO solution is the industry''s first OCI MSA capable platform and built with GF''s proven silicon photonics technology MALTA, N.Y., May 04, 2026 (GLOBE NEWSWIRE) --

SILICON PHOTONICS, LINEAR DRIVE PLUGGABLE AND CO

Our research covers the whole supply chain from optical and semiconductor components, to modules, sub-systems and their applications in telecom and datacom systems.

Coherent Showcases Multiple Co-Packaged Optics (CPO)

Table of Contents Coherent''s OFC 2026 Demonstrations: What to Expect At OFC 2026, Coherent will show off several new breakthroughs in co-packaged optics. One highlight is a 6.4T

LIVE WEBINAR | CO-PACKAGED OPTICS: POWERING THE NEXT

How Co-Packaged Optics enables optical-electrical convergence The role of silicon photonics in next-generation data centers Advanced packaging innovations: hybrid bonding, heterogeneous

2.5D Heterogeneous Integration for Silicon Photonics Engines in

With integration, as the optical modules get smaller and are co-packaged with electrical host ASIC, the power at this interface can be reduced. With even tighter integration, we may not need a DSP inside

Co-Packaged Optics (CPO)Co-Packaged Optics (CPO)

Co-packaged optics overcomes these limitations by placing the optical engine much closer to the switching silicon. Its success depends on advanced semiconductor

Co-packaged Optics Market 2026-2034 Analysis:

Co-packaged Optics Market 2026-2034 Analysis: Trends, Competitor Dynamics, and Growth Opportunities Co-packaged Optics Market by Component (Optical

TSMC''s Silicon Photonics Architecture: Why Couplers

Through platforms such as COUPE, EPIC-BOE, and iOIS, TSMC is steadily building a comprehensive ecosystem to support Co-Packaged Optics

Where co-packaged optics (CPO) technology stands in

Co-packaged optics (CPO) technology, a key enabler for next-generation data center architectures, promises unprecedented bandwidth density

EUV: Corgi Lithography & Semiconductor Photonics ETF Launched in

Sergey (@SergeyCYW). 215 likes 4 replies. EUV: Corgi Lithography & Semiconductor Photonics ETF Launched in early May 2026, EUV targets one of AI''s next bottlenecks: moving data

Co-Packaged Optics — a deep dive | APNIC Blog

The Broadcom Bailly chip integrates 6.4Tbps silicon-photonics-based optical engines inside the ASIC package. These high-density edge-mounted

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